

### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	-60	V
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) $V_{GS}$ = -10V	T <sub>C</sub> = +25°C T <sub>C</sub> = +70°C	Ι <sub>D</sub>	-7.8 -6.3	А
	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	Ι <sub>D</sub>	-3.3 -2.7	А
Pulsed Drain Current (380µs Pulse, 1% Duty Cycle)		I <sub>DM</sub>	-24	A
Maximum Continuous Body Diode Forward Current (Note 6)		IS	-1.8	А
Avalanche Current (Note 9) L = 0.1mH		I <sub>AS</sub>	-19	А
Avalanche Energy (Note 9) L = 0.1mH		E <sub>AS</sub>	18	mJ

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Bower Dissipation (Noto 5, 8, 7)	T <sub>A</sub> = +25°C		1.2	W
Total Power Dissipation (Note 5 & 7)	T <sub>A</sub> = +70°C	PD	0.9	
Total Power Dissipation (Note 5 & 8)	T <sub>A</sub> = +25°C		1.2	
Thermal Resistance, Junction to Ambient (Note 5 & 7)	Steady State		104	°C/W
	t<10s	R <sub>OJA</sub>	45	
Thermal Resistance, Junction to Ambient (Note 5 & 8)	Steady State		100	
Total Power Dissipation (Note 6 & 7)	T <sub>A</sub> = +25°C		1.7	W
	T <sub>A</sub> = +70°C	PD	1.1	
Total Power Dissipation (Note 6 & 8)	T <sub>A</sub> = +25°C		1.8	
Thermal Resistance, Junction to Ambient (Note 6 & 7)	Steady State		74	°C/W
	t<10s	R <sub>OJA</sub>	37	
Thermal Resistance, Junction to Ambient (Note 6 & 8)	Steady State		71	
Thermal Resistance, Junction to Case (Note 6 & 7)		R <sub>OJC</sub>	15	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. For a dual device with one active die.

8. For a device with two active die running at equal power. 9. Ias and Eas rating are based on low frequency and duty cycles to keep  $T_J = +25^{\circ}C$ .

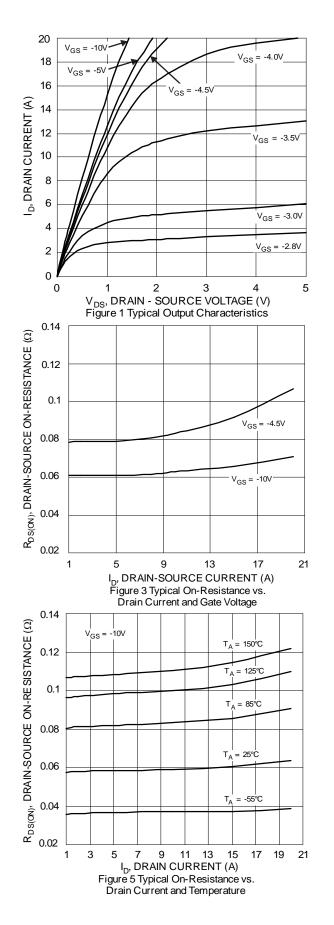


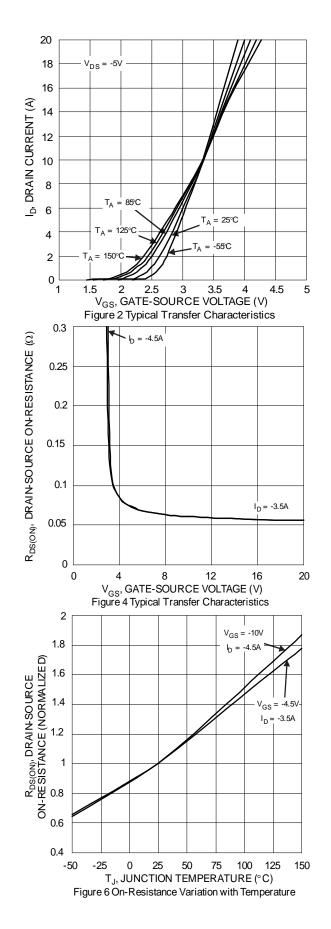
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

		-					
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 10)	•	-					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-60	—		V	$V_{GS} = 0V, I_D = -250 \mu A$	
Zero Gate Voltage Drain Current TJ = +25°C	IDSS	—	—	-1	μA	$V_{DS} = -48V$ , $V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>			100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 10)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1		-3	V	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	
Static Drain-Source On-Resistance	Brayers	—	—	105	mΩ	$V_{GS} = -10V, I_D = -4.5A$	
	R <sub>DS(ON)</sub>		—	130	11152	$V_{GS} = -4.5V, I_D = -3.5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	CISS	_	969		pF		
Output Capacitance	Coss		57		pF	VDS = -30V, VGS = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>RSS</sub>		44		pF		
Gate Resistance	R <sub>G</sub>	_	13.7	—	Ω	VDS = 0V, VGS = 0V, f = 1.0MHz	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Q <sub>G</sub>	—	8.2	—	nC	VDS = -30V, ID = -12A	
Total Gate Charge (V <sub>GS</sub> = -10V)	Q <sub>G</sub>	_	17.2	_	nC	VDS = -30V, ID = -12A	
Gate-Source Charge	Q <sub>GS</sub>	—	3.0	—	nC		
Gate-Drain Charge	Q <sub>GD</sub>	_	3.1		nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.4	_	ns	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -30V, R <sub>GEN</sub> =	
Turn-On Rise Time	t <sub>R</sub>	_	23	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>		34		ns	3Ω, ID=-12A	
Turn-Off Fall Time	tF	_	42		ns	1	
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	13.2		ns	I <sub>S</sub> = -12A, di/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	6.18		nC		

 Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing. Notes:



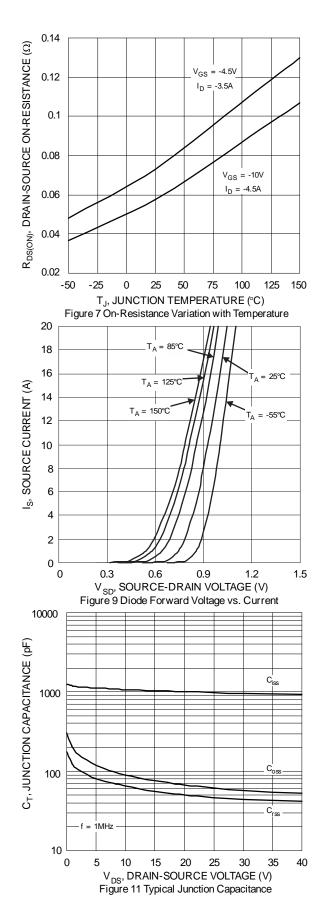


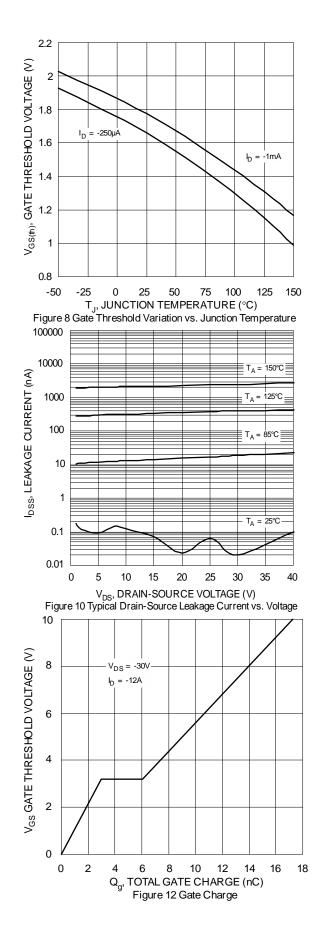


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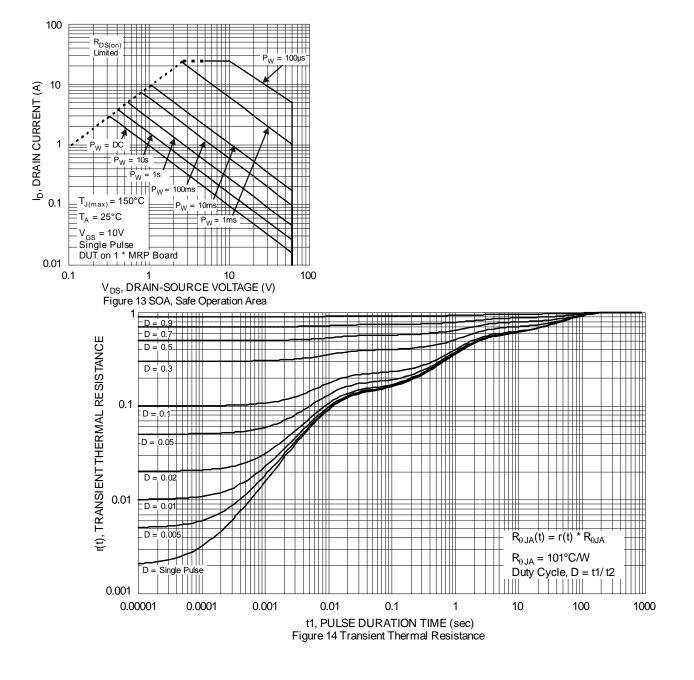






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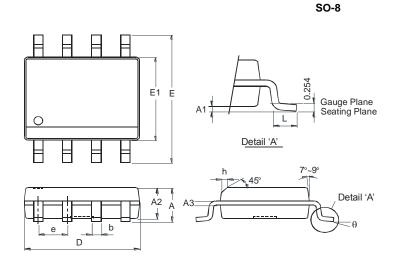






## **Package Outline Dimensions**

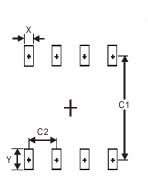
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	1.27 Typ			
h	_	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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